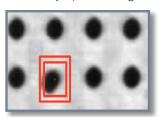


# TR7600X SII CT SERIES

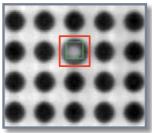
- Ultra-Fast 3D Inline AXI
- Rapid Intelligent Programming
- Automated Defect Evaluation
- Precise 3D CT Imaging

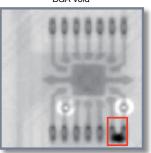
AUTOMATED
X-RAY INSPECTION

# **Defect Symptom Images**

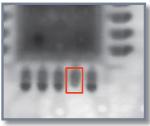


BGA Head-In-Pillow

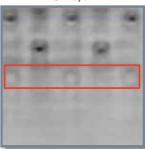




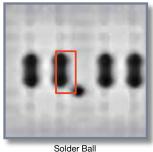
Bridging



QFN Open



PressFit Pin Defect



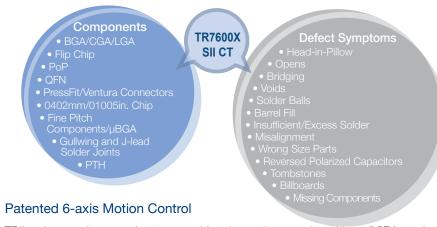
# Maximum Performance Inline 3D Automated X-ray Inspection

- Ultra-fast inline automated X-ray inspection of PCBAs
- 2D + 3D images using multiple bidirectional angled cameras
- Automated inspection and pass/fail evaluation
- User selectable X-ray power up to 130 kV/ 300 μA
- Patented 6-axis motion control for maximum flexibility
- Edge-to-edge large board inspection up to 900 x 460 mm
- Advanced 3D CT capability for vertical slicing of complex solder joints

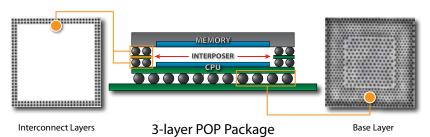
#### Intelligent Software Solution

- Intelligent CAD or image-based programming wizard
- Intelligent detection of solder and assembly defects
- Automatic image quality enhancement for overlapping components and complex defects
- Automatic board warp compensation
- Automated 3D slice extraction

# **Defect Detection Capability**



TRI's unique motion control system provides clearest images of multi-layer PCBAs and overlapping components, enabling reliable automated inspection of dual-side PCB assemblies without typical shadowing issues.



#### **BlockScan Customized Imaging**

BlockScan module enhances AXI test program coverage by re-scanning selected areas of the tested board using customized system settings. This improves image quality and automated defect detection for most complex PCBAs, including fine pitch µBGAs, PressFit and metal shielded components. Using BlockScan, TRI AXI can reliably inspect up to 3-layer PoP packages.



Multiple Resolutions in One Program

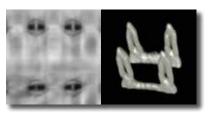
## 3D CT Inspection

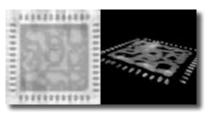
Enhanced 3D inspection with planar CT imaging can recreate a complete 3D model of each solder joint, enabling clear analysis of shape irregularities, head-in-pillow and voiding problems. Vertical cross-section CT images help with reliable visual review of borderline and buried solder joints.



#### Enhanced Defect Visualization with CT

CT data processing helps clearly visualize solder defects such as voiding, bridging and deformities.





3D CT displays solder joints and defects in much more detail than traditional 3D X-ray slicing

#### Eliminate Board Warp Issues

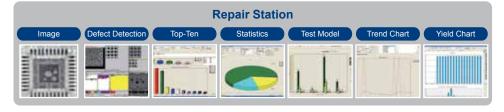
The TR7600X SII CT uses multiple laser sensors to accurately measure any PCB assembly deformation and automatically adjusts component inspection parameters to compensate for local board warpage. This ensures reliable inspection of the most complex boards with overlapping and multi-layered components and heavy PressFit connectors.

#### Radiation Safe Design

Designed with safety in mind, TRI's AXI systems have full lead shielding which prevents harmful exposure in everyday use and reduces X-ray leakage below background radiation levels of 0.5  $\mu$ Sv/hr. The certified safety design conforms to USFDA Code of Federal Regulations Title 21, Part 1020.40.

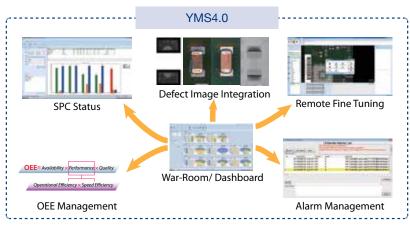
#### Repair Station

The TR7600X SII CT collects a wide range of inspection data to offer instantaneous process monitoring and analysis. This integrated approach offers clear statistical feedback that improves defect management and enhances the efficiency of the inspection process.

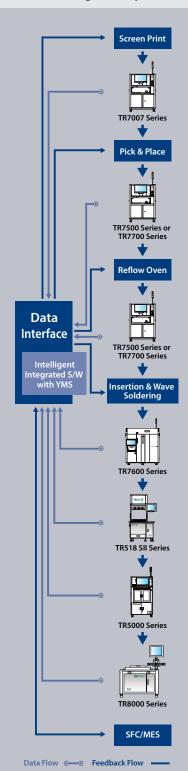


#### Industry 4.0 Production Line Integration

YMS 4.0 lets TRI inspection solutions interface and share inspection data with the shop floor system and other inspection machines. With the central console an operator can control, track, analyze and optimize the inspection process across the entire production line and obtain real actionable data to optimize production quality in the Industry 4.0 environment.



#### Yield Management System



- Inspection results and data integration
- Real time SPC and production yield management
- Quality reports and closed loop tracking
- Support defect component analysis and improvements
- Knowledge Management (KM)
- Productivity and Quality Management

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# X-Ray & Imaging System

A-ray Source	130 kv max (user adjustable)
Image Resolutions	10 μm, 15 μm, 20 μm (factory setting)
Camera	High-performance, bidirectional line-scan cameras
Inspection Functions	
Component Level Defects	Missing, Misalignment, Tombstone, Billboard, Tantalum Polarity & Rotation, Floating

Insufficient/Excess Solder, Bridging, Open, Solder Ball, Non-

100 ld/ may (vacy adjustable)

wetting, Void & Lifted Lead

# X-Y Table & Control

Joint Level Defects

High-precision ball screw/servo motor with DSP-based motion controller

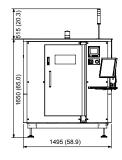
X-Y Axis Resolution 1 μm

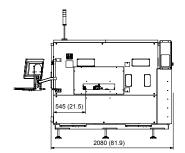
# PCB & Conveyor System

Min. PCB Size	50 x 50 mm (1.97 x 1.97 in.)
Max. PCB Size	900 x 460 mm (35.4 x 18.1 in.)
PCB Thickness	0.6 - 5 mm
PCB Transport Height	880 – 920 mm (34.6 – 36.2 in.)*
Max. PCB Weight	3 kg (7 lbs) [8 kg (18 lbs) optional]
PCB Carrier/Fixing	Step motor driven conveyor & pneumatic clamping
Clearance	
Top 20 μm	50 mm (1.97 in.)
15 µm	30 mm (1.18 in.)
10 µm	15 mm (0.59 in.)
Bottom	40 mm (1.58 in.)
Edge	3 mm (0.12 in.)

<sup>\*</sup> SMEMA Compatible

#### **Dimensions**





Unit: mm (in.)

Weight	3250 kg (7165 lbs)
Power Requirement	200 – 240 VAC single phase,
	50/60 Hz, 4 kVA
Air Requirement	72 psi – 87 psi (5 – 6 bar)

## **Optional Accessories**

Barcode Scanner, Repair Station, Offline Editor & Yield Management System (YMS 4.0), YMS Lite

TRI has a patent in System and Method for Laminography Inspection

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